

Title (en)  
Installation and corresponding process for hot application of an adhesive composition

Title (de)  
Anlage und entsprechendes Heianwendungsverfahren einer Klebezusammensetzung

Title (fr)  
Installation et procd correspondant d'application  chaud d'une composition adhsive

Publication  
**EP 2878364 A1 20150603 (FR)**

Application  
**EP 14195521 A 20141128**

Priority  
FR 1361818 A 20131129

Abstract (en)  
[origin: US2015152292A1] A system for hot application of an adhesive composition, comprising an in-line heating device and a corresponding method for hot application of the adhesive composition. The system comprises: an application nozzle for applying the adhesive composition; a supply line for supplying the nozzle with the adhesive composition to be applied in fluid form; a in-line heating device for heating of the adhesive composition to an application temperature, the heating device comprising: a static mixture including an electrically conducting material, and an inductive cable surrounding the static mixer.

Abstract (fr)  
Installation d'application  chaud d'une composition adhsive comprenant un dispositif de chauffage en ligne et procd correspondant d'application  chaud de la composition adhsive. L'installation comprend : - une buse d'application de la composition adhsive ; - une ligne d'alimentation de la buse avec la composition adhsive  appliquer sous forme fluide ; - un dispositif de chauffage en ligne de la composition adhsive  une temprature d'application, le dispositif de chauffage (22) comprenant : \* un mlangeur statique (30) comportant un matriau conducteur lectriquement, et \* un cble inducteur (26) entourant le mlangeur statique (30).

IPC 8 full level  
**B01F 23/80** (2022.01); **B05C 5/00** (2006.01); **B05C 5/02** (2006.01); **B05C 11/10** (2006.01); **B29B 13/02** (2006.01)

CPC (source: EP US)  
**B01F 23/811** (2022.01 - EP US); **B01F 25/43161** (2022.01 - EP US); **B01F 35/92** (2022.01 - EP US); **B01F 35/95** (2022.01 - EP US); **B05B 1/24** (2013.01 - US); **B05B 7/16** (2013.01 - US); **B05C 11/1042** (2013.01 - EP US); **B05D 1/02** (2013.01 - US); **B05D 1/26** (2013.01 - US); **B05D 5/10** (2013.01 - US); **B29B 13/022** (2013.01 - EP US); **C09J 5/06** (2013.01 - US); **B01F 2035/99** (2022.01 - EP US); **B05B 15/20** (2018.01 - EP US); **B05C 5/0254** (2013.01 - EP US)

Citation (applicant)  
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• JP 2001191364 A 20010717 - ASAHI KASEI CORP  
• JP 2001191380 A 20010717 - ASAHI KASEI CORP  
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Designated contracting state (EPC)  
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Designated extension state (EPC)  
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